Hybrid 8j376 Traveler

July 20, 2000

1 Connectivity

Repairs on shorts:
Fixes for opens:

2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 8J376 has die: 244-126 244-128 244-131 244-132 240-063 221-074 240-075 240-076

3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

```
% Hybrid 8j376 classification info. Created 12:40:06 07/20/00

Hybrid 8j376 quality: fair
Chip classification: fair good fair fair fair fair fair fair
Bad channels (chip-channel): 0-104 3-17 4-1 4-67 5-13 6-27 7-64
Bad cells: none
Random bad capacitors (chip-cell-channel): 2-33-121 2-9-121
Channels at pedestal needed for DCMS: 32.1 31.8 31.8 32.8 30.8 31.8 30.9 31.8
```

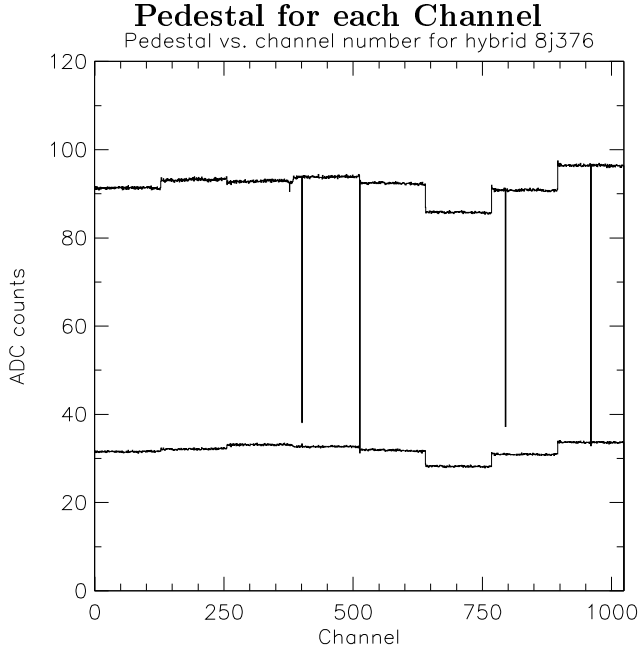
4 Comments

HV tested.

5 Pedestal

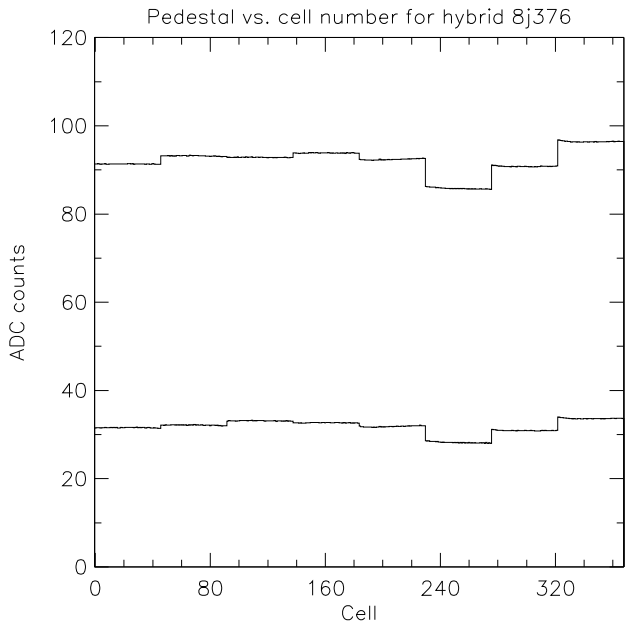
The following plot shows the pedestals vs. channel number with and without charge injection:

Pedestal for each Channel



The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

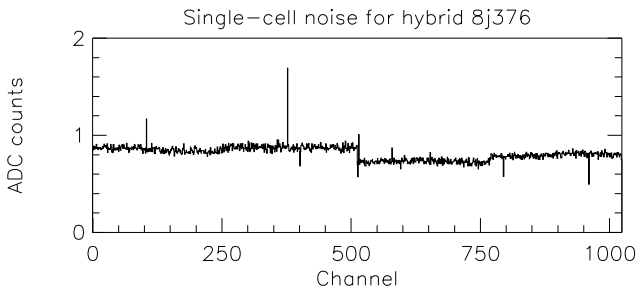
Pedestal vs. Pipeline Cell ID

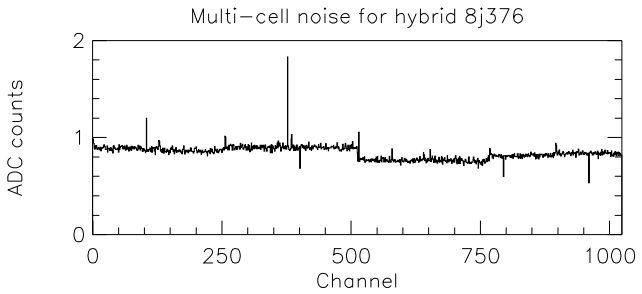


6 Noise

The following plots show the single-cell and multi-cell RMS noise:

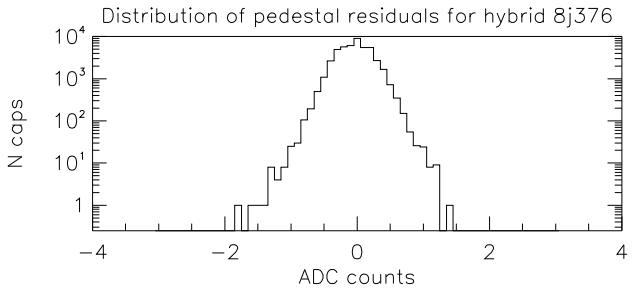
RMS Noise

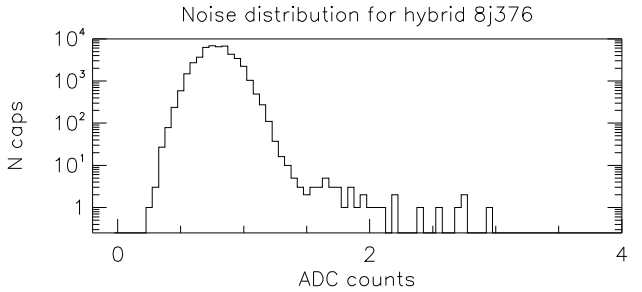




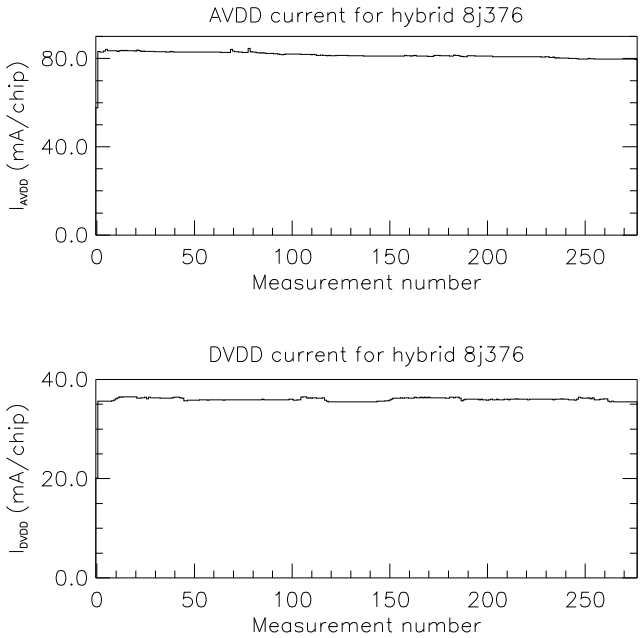
The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

Distribution of Pedestals and Noise





7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

Supply Currents During Burn-in